

74AHCT541A

Octal buffer/line driver; 3-state

Rev. 1 — 23 December 2015

Product data sheet

1. General description

The 74AHCT541A is an 8-bit buffer/line driver with 3-state outputs and TTL inputs. The device features two output enables ($\overline{OE}1$ and $\overline{OE}2$). A HIGH on $\overline{OE}n$ causes the associated outputs to assume a high-impedance OFF-state.

Designed to operate over a V_{CC} range from 4.5 V to 5.5 V, the inputs are TTL compatible, which allows the device to be used to translate from 3.3 V to 5 V.

Schmitt-trigger action at all inputs makes the circuit tolerant of slower input rise and fall times.

This device is fully specified for partial Power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

2. Features and benefits

- Direct interface with TTL levels
- Supply voltage range from 4.5 V to 5.5 V
- Typical t_{pd} of 2.8 ns at 5 V
- Typical $V_{OL(p)} < 0.8$ V at $V_{CC} = 5$ V, $T_{amb} = 25$ °C
- Typical $V_{OH(v)} > 2.3$ V at $V_{CC} = 5$ V, $T_{amb} = 25$ °C
- Supports mixed-mode voltage operation on all ports
- I_{OFF} circuitry provides partial Power-down mode operation
- Latch-up performance exceeds 250 mA per JESD 78 Class II
- ESD protection:
 - ◆ HBM ANSI/ESDA/JEDEC JS-001 Class 2 exceeds 3kV
 - ◆ MM JESD22-A115-A exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 2kV
- Multiple package options
- Specified from -40 °C to $+85$ °C and from -40 °C to $+125$ °C



3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74AHCT541APW	-40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74AHCT541ABQ	-40 °C to +125 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1

4. Functional diagram

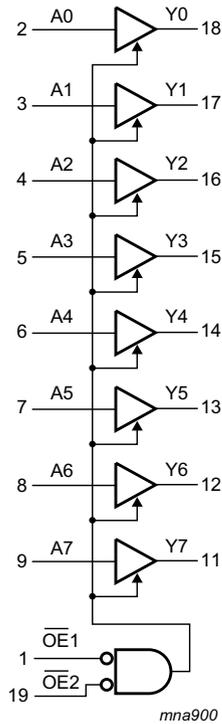


Fig 1. Logic symbol

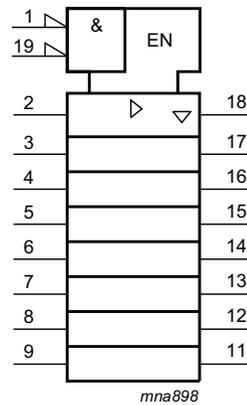
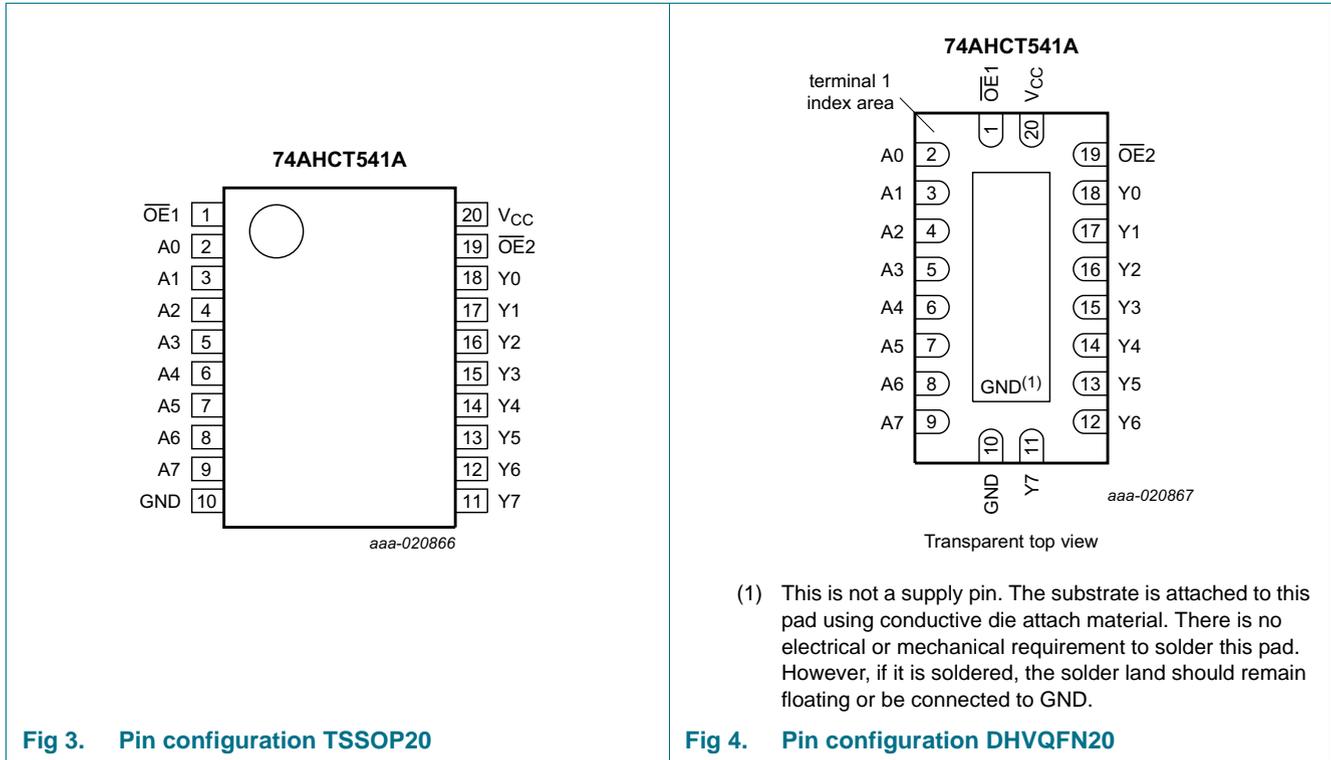


Fig 2. IEC logic symbol

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{OE}1$	1	output enable input (active LOW)
A0 to A7	2, 3, 4, 5, 6, 7, 8, 9	data input
GND	10	ground (0 V)
Y0 to Y7	18, 17, 16, 15, 14, 13, 12, 11	data output
$\overline{OE}2$	19	output enable input (active LOW)
V _{CC}	20	supply voltage

6. Functional description

Table 3. Functional table^[1]

Control		Input	Output
OE1	OE2	An	Yn
L	L	L	L
L	L	H	H
X	H	X	Z
H	X	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
V_I	input voltage		-0.5	+7.0	V
V_O	output voltage	active mode	-0.5	$V_{CC} + 0.5$	V
		power-down or 3-state mode	-0.5	+7.0	V
I_{IK}	input clamping current	$V_I < 0$ V	-20	-	mA
I_{OK}	output clamping current	$V_O < 0$ V	-20	-	mA
I_O	output current	$V_O = 0$ V to V_{CC}	-	± 25	mA
I_{CC}	supply current		-	75	mA
I_{GND}	ground current		-75	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C	-	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] This value is limited to 7.0 V maximum.

[4] For TSSOP20 package: above 100 °C the value of P_{tot} derates linearly with 10 mW/K.
For DHVQFN20 package: above 110 °C the value of P_{tot} derates linearly with 12.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions
 Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		4.5	5.5	V
V_I	input voltage		0	5.5	V
V_O	output voltage	active mode	0	V_{CC}	V
		power-down or 3-state mode	0	5.5	V
T_{amb}	ambient temperature		-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 5.0\text{ V} \pm 0.5\text{ V}$	-	20	ns/V

9. Static characteristics

Table 6. Static characteristics
 Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V_{IH}	HIGH-level input voltage	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	2	-	-	2	-	2	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	0.8	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 4.5\text{ V}$								
		$I_O = -50\ \mu\text{A}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -8\text{ mA}$	3.94	-	-	3.8	-	3.7	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 4.5\text{ V}$								
		$I_O = 50\ \mu\text{A}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 8\text{ mA}$	-	-	0.36	-	0.44	-	0.55	V
I_{OZ}	OFF-state output current	$V_{CC} = 5.5\text{ V}$; $V_I = V_{IH}$ or V_{IL} ; $V_O = \text{GND to }5.5\text{ V}$	-	-	± 0.25	-	± 2.5	-	± 2.5	μA
I_{OFF}	power-off leakage current	V_I or $V_O = \text{GND to }5.5\text{ V}$; $V_{CC} = 0\text{ V}$	-	-	0.5	-	5	-	5	μA
I_I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 0\text{ V to }5.5\text{ V}$	-	-	0.1	-	1	-	1	μA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0\text{ A}$; $V_{CC} = 5.5\text{ V}$	-	-	2	-	20	-	20	μA
ΔI_{CC}	additional supply current	per input pin; $V_I = 3.4\text{ V}$; $I_O = 0\text{ A}$; other pins at V_{CC} or GND; $V_{CC} = 5\text{ V}$	-	-	1.35	-	1.5	-	1.5	mA

10. Dynamic characteristics

Table 7. Dynamic characteristics
GND = 0 V. For test circuit see Figure 7.

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	Min	Max	
t _{pd}	propagation delay	An to Y _n ; see Figure 5 ^[2]								
		V _{CC} = 4.5 V to 5.5 V								
		C _L = 15 pF	-	2.8	6.9	1	8	1	8	ns
		C _L = 50 pF	-	4.4	7.9	1	9	1	9	ns
t _{en}	enable time	OEn to Y _n ; see Figure 6								
		V _{CC} = 4.5 V to 5.5 V								
		C _L = 15 pF	-	3.9	11.3	1	13	1	13	ns
		C _L = 50 pF	-	5.5	12.3	1	14	1	14	ns
t _{dis}	disable time	OEn to Y _n ; see Figure 6 ^[2]								
		V _{CC} = 4.5 V to 5.5 V								
		C _L = 15 pF	-	3.6	7.5	1	8	1	8	ns
		C _L = 50 pF	-	5.4	11.9	1	13.5	1	13.5	ns
t _{sk(o)}	skew	V _{CC} = 4.5 V to 5.5 V; C _L = 50 pF	-	-	1	-	1	-	1	ns
C _I	input capacitance	V _I = V _{CC} or GND; V _{CC} = 5 V	-	2	6	-	6	-	6	pF
C _O	output capacitance	V _O = V _{CC} or GND; V _{CC} = 5 V	-	5	-	-	-	-	-	pF
C _{PD}	power dissipation capacitance	per buffer; ^[3] C _L = 50 pF; f = 10 MHz; V _I = GND to V _{CC}	-	8	-	-	-	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 5 V.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

t_{en} is the same as t_{PZL} and t_{PZH}.

t_{dis} is the same as t_{PLZ} and t_{PHZ}.

[3] C_{PD} is used to determine the dynamic power dissipation P_D (μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

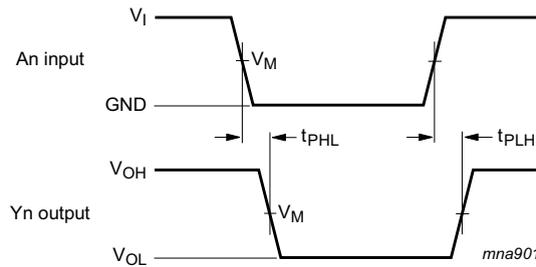
C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts.

Table 8. Noise characteristics
 GND = 0 V. For test circuit see [Figure 7](#).

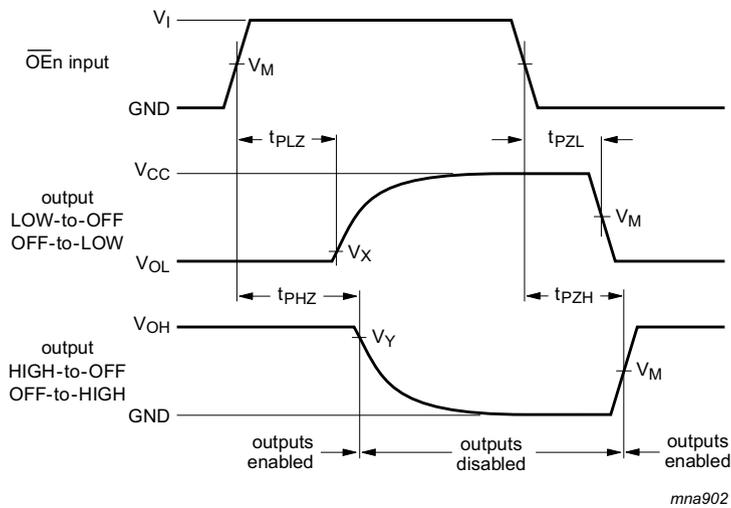
Symbol	Parameter	Conditions	T _{amb} = 25 °C			Unit
			Min	Typ	Max	
V_{CC} = 5 V; C_L = 50 pF						
V _{OL(p)}	LOW-level output voltage (peak)		-	0.5	1.5	V
V _{OL(v)}	LOW-level output voltage (valley)		-1.5	-0.3	-	V
V _{OH(v)}	HIGH-level output voltage (valley)		-	4.5	-	V
V _{IH(AC)}	AC HIGH-level input voltage (dynamic)		2	-	-	V
V _{IL(AC)}	AC LOW-level input voltage (dynamic)		-	-	0.8	V

11. Waveforms



Measurement points are given in [Table 9](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 5. Propagation delay input (An) to output (Yn)



Measurement points are given in [Table 9](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. enable and disable times

Table 9. Measurement points

Input	Output		
V_M	V_M	V_X	V_Y
1.5 V	$0.5V_{CC}$	$V_{OL} + 0.3 V$	$V_{OH} - 0.3 V$

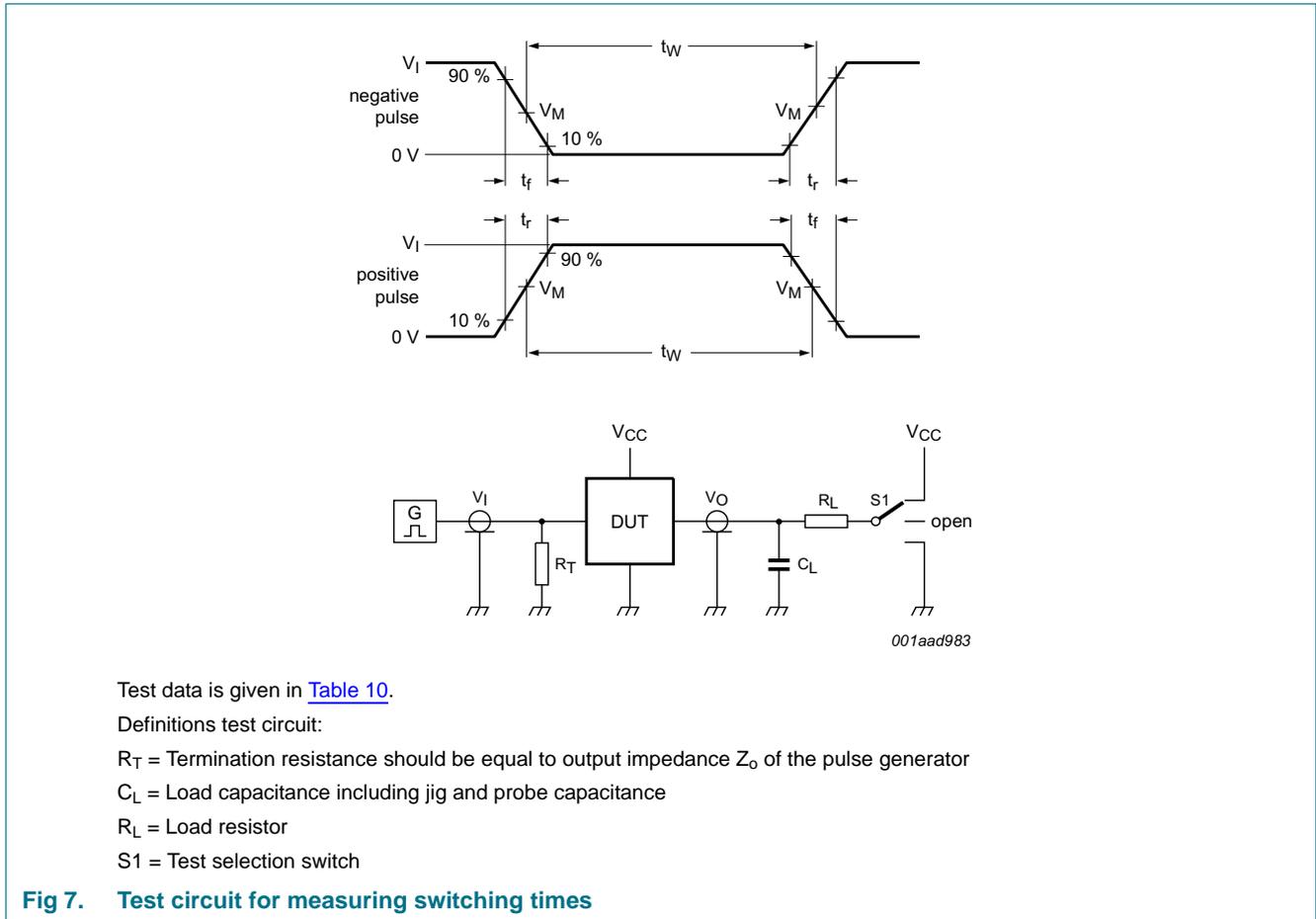


Fig 7. Test circuit for measuring switching times

Table 10. Test data

Input		Load		S1 position		
V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
GND to 3.0 V	3.0 ns	15 pF, 50 pF	1 kΩ	open	GND	V_{CC}

12. Package outline

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

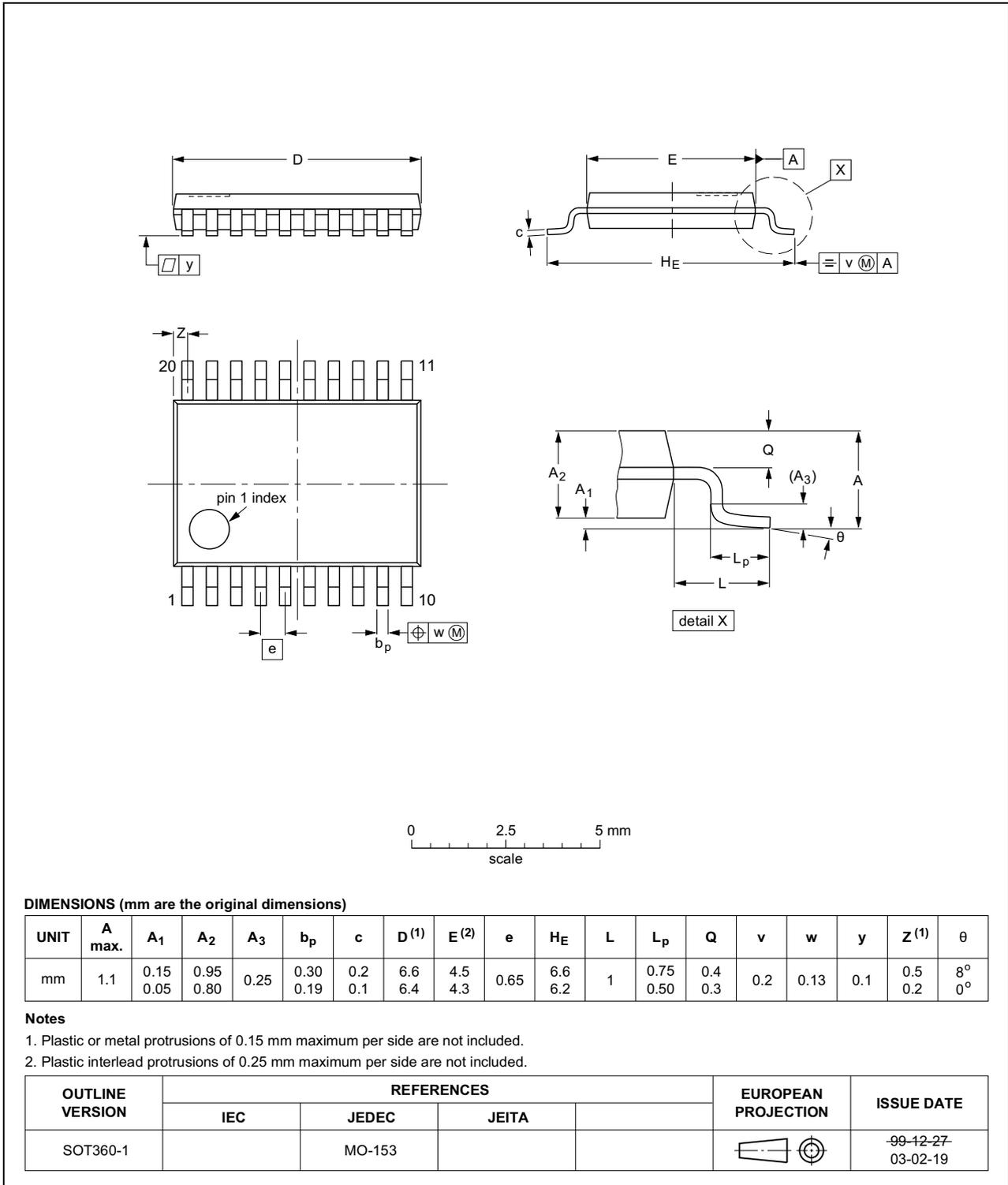


Fig 8. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

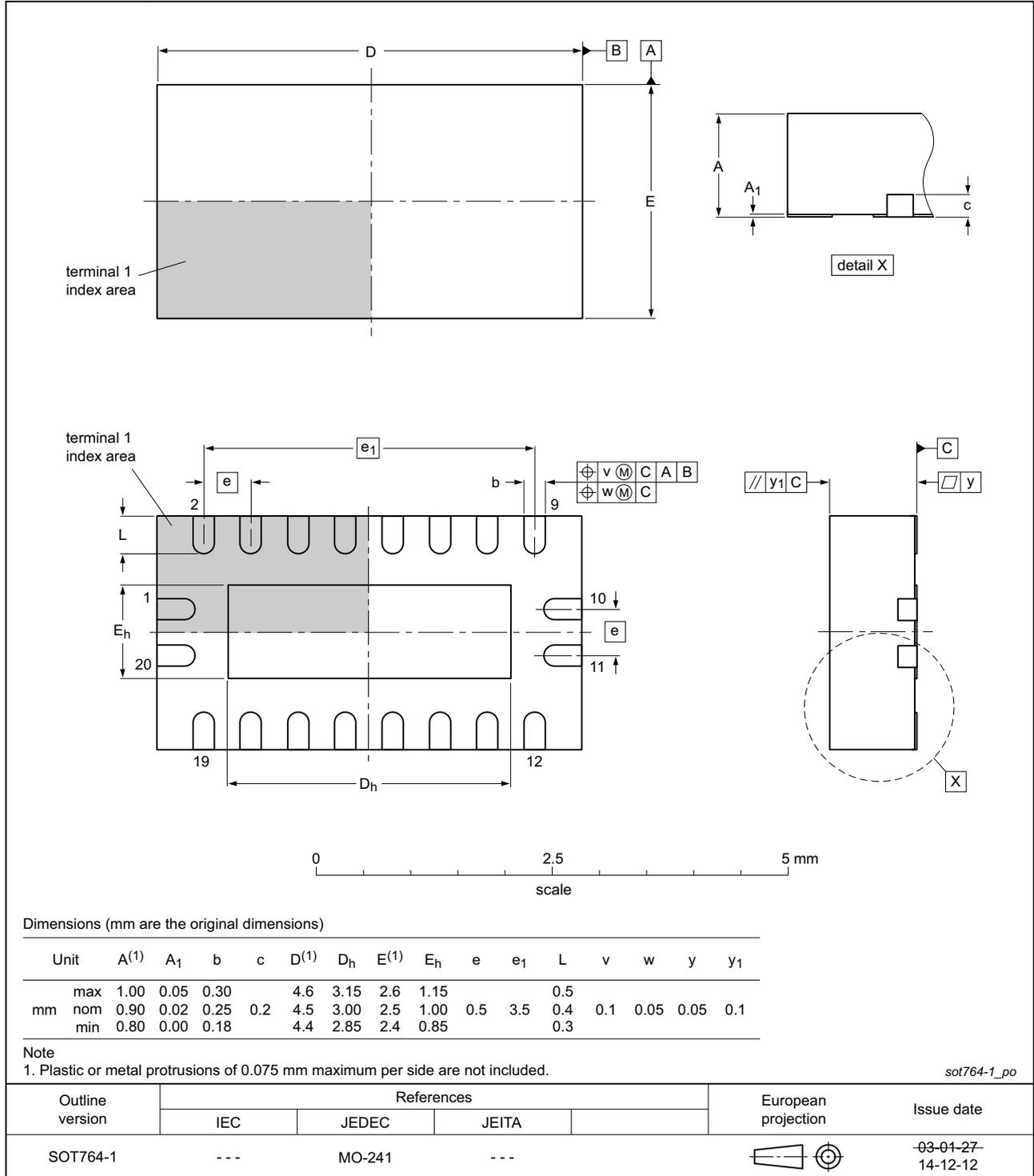


Fig 9. Package outline SOT764-1 (DHVQFN20)

13. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charge Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHCT541A v.1	20151223	Product data sheet	-	-

15. Legal information

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Document status ^{[1][2]}	Product status ^[3]	Definition
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[2] The term 'short data sheet' is explained in section "Definitions".

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